Schottky Barrier Diode

These Schottky barrier diodes are designed for high speed switching applications, circuit protection, and voltage clamping. Extremely low forward voltage reduces conduction loss. Miniature surface mount package is excellent for hand held and portable applications where space is limited.

- Extremely Fast Switching Speed
- Extremely Low Forward Voltage 0.5 V (max) @ $I_F = 200 \text{ mA}$
- Low Reverse Current

MAXIMUM RATINGS

Rating	Symbol	Value	Unit	
Reverse Voltage	V_R	30	Vdc	
Forward Current DC	lF	200	mA	
ESD Rating: Class 1C per Human Body Model Class C per Machine Model				

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board, (Note 1) T _A = 25°C	P _D	200	mW
Derate above 25°C		1.57	mW/°C
Thermal Resistance Junction-to-Ambient	$R_{\theta JA}$	635	°C/W
Junction and Storage Temperature Range	T _J , T _{stg}	-55 to +125	°C

1. FR-5 Minimum Pad

ELECTRICAL CHARACTERISTICS

(T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Leakage (V _R = 10 V)	I _R	-	-	30.0	μΑ
Forward Voltage (I _F = 200 mA)	V _F	1	-	0.50	Vdc



ON Semiconductor®

http://onsemi.com

30 V SCHOTTKY BARRIER DIODE





SOD-523 CASE 502 PLASTIC

MARKING DIAGRAM



5M = Specific Device Code d = Date Code

ORDERING INFORMATION

Device	Package	Shipping†
RB521S30T1	SOD-523	4 mm Pitch 3000/Tape & Reel
RB521S30T5	SOD-523	2 mm Pitch 8000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

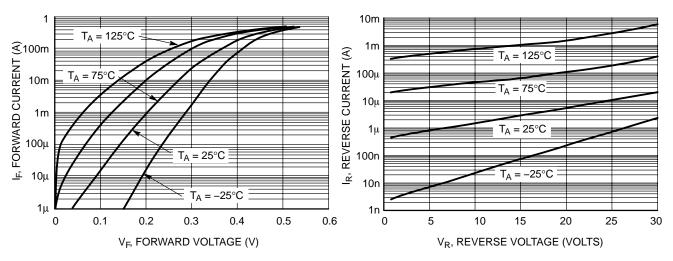


Figure 1. Forward Characteristics

Figure 2. Reverse Characteristics

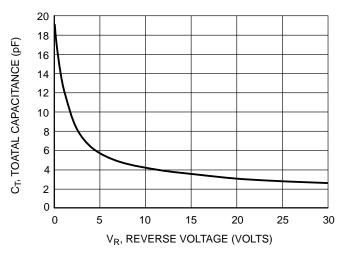
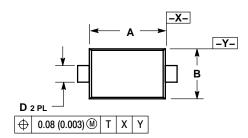
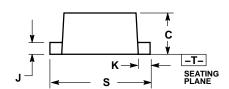


Figure 3. Total Capacitance

PACKAGE DIMENSIONS

SOD-523 PLASTIC PACKAGE CASE 502-01 ISSUE O

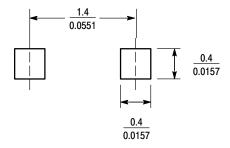




- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M,
- DIMENSIONING AND TOLEHANCING PEH ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
 MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.10	1.20	1.30	0.043	0.047	0.051
В	0.70	0.80	0.90	0.028	0.032	0.035
С	0.50	0.60	0.70	0.020	0.024	0.028
D	0.25	0.30	0.35	0.010	0.012	0.014
J	0.07	0.14	0.20	0.0028	0.0055	0.0079
K	0.15	0.20	0.25	0.006	0.008	0.010
S	1.50	1.60	1.70	0.059	0.063	0.067

RECOMMENDED FOOTPRINT



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